GONDA
光达科技

明星产品
Flagship products

HJT低温主栅浆料：GL001系列
HJT Low-Temperature Busbar Paste: GL001 Series
HJT低温细栅浆料：GH011系列
HJT Low-Temperature Finger Paste: GH011 Series

适用范围
Application

- 适配热风低温烘箱固化（固化区间 140–250℃）
  Suitable for low-temperature hot-air oven curing (curing temperature range: 140~250°C)

亮点
Highlights

- 保证焊接拉力稳定，同时降低体电阻率
  Ensures stable solder pull strength while simultaneously reducing bulk resistivity.
- 全系固化温度 140–250℃，不会破坏非晶硅钝化层与 TCO 透明导电膜
  Full-series curing temperature of 140~250°C without damaging the a-Si passivation layer and TCO (Transparent Conductive Oxide) film.
- 适配11-20μm开口的PI网版/钢版细线快速印刷，覆盖常规分段主栅、0BB无主栅、激光转印等主流金属化工艺
  Compatible with fast fine-line printing using PI (polyimide) screens / stainless steel stencils with 11-20μm openings. Covers mainstream metallization processes, including conventional segmented busbars, 0BB (Zero Busbar), and laser transfer printing.

项目 Item		HJT细栅GH011系列 HJT Fine Grid GH011	HJT主栅GL001系列 HJT Busbar GL001	测试方法 Test Method
银浆性能 Paste Properties	颜色、外观 (Color, Appearance)	银灰色浆料 (Silver-gray paste)	银灰色浆料 (Silver-gray paste)	目测 (Visual inspection)
	粘度（pa·s,25℃） Viscosity	120-220	120-220	TA流变仪/10RPM TA Rheometer/10RPM
	触变性 Thixotropy	≥5	≥5	10rpm/100rpm 粘度比值 Viscosity ratio at 10rpm/100rpm
	细度 Fineness of grind	≤10μm	≤10μm	细度板 Grindometer
	银含(%) Silver content	91-94	90-93	烧失法 (TGA)
	储存时间/储存温度 Storage period / Temp	6个月/-40℃ 6 months / 40°C	6个月/-40℃ 6 months / 40°C	
	建议网版开口宽度(μm) Recommended opening width	≥15	≥20	
	固化条件 Curing conditions	200℃/5-10min	200 ℃/5-10min	ITO硅片 ITO wafer/substrate
	体电阻率（μΩcm） Bulk resistivity	3.5 - 5.5	5.5 - 7.5	四探针测试仪 Four-point probe tester
固化后性能 Cured Properties	焊接拉力(N/mm,ITO) Solder pull strength	0.5 - 1.0	1.5 - 3.5	低温焊带 Low-temperature solder ribbon